

L Number	Hits	Search Text	DB	Time stamp
-	1715	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.	USPAT; US-PGPUB	2004/05/04 11:22
-	11	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer\$4 with chamber with remov\$3 with oxide)	USPAT; US-PGPUB	2003/05/30 16:14
-	152	transfer\$4 with chamber with remov\$3 with oxide	USPAT; US-PGPUB	2003/05/29 20:25
-	0	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer\$4 with chamber with "hf")	USPAT; US-PGPUB	2003/05/29 20:29
-	260	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer\$4 with chamber with (gas vapor))	USPAT; US-PGPUB	2003/05/29 20:33
-	29	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer\$4 with chamber with (gas vapor) with remov\$3)	USPAT; US-PGPUB	2003/05/29 20:41
-	2	"11134684"	JPO; DERWENT	2003/05/29 20:49
-	163	sugiura.in. and tokyo.as.	JPO; DERWENT	2003/05/29 20:49
-	6	sugiura.in. and tokyo.as. and "uv"	JPO; DERWENT	2003/05/29 20:49
-	6	("5228206" "5972161" "6143081" "6178660" "6204120" "6232248").PN.	USPAT	2003/05/29 20:53
-	2	6178660.URPN.	USPAT	2003/05/29 21:00
-	0	6467491.URPN.	USPAT	2003/05/29 21:00
-	13	("4795299" "4917556" "5228206" "5423971" "5529657" "5611861" "5755938" "5759334" "5855675" "5863170" "5880924" "5882165" "5886864").PN.	USPAT	2003/05/29 21:01
-	112	imahashi.in.	USPAT; US-PGPUB	2003/05/30 10:14
-	2	imahashi.in. and 118/719.ccls.	USPAT; US-PGPUB	2003/05/30 10:15
-	50	5695564.URPN.	USPAT	2003/05/30 10:31
-	1715	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.	USPAT; US-PGPUB	2003/05/30 10:38
-	94	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer\$4 with chamber with (inlet ((vapor gas) with suppl\$3)))	USPAT; US-PGPUB	2003/05/30 10:41
-	54	c23c016\$.ipc. and (transfer\$4 with chamber with (inlet suppl\$3) with (vapor gas))	EPO; JPO; DERWENT	2003/05/30 11:21
-	71	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer\$4 with chamber with (inlet suppl\$3) with (vapor gas))	USPAT; US-PGPUB	2003/05/30 10:51
-	0	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ((transfer\$4 with chamber with (inlet suppl\$3) with (vapor gas)) same align\$4)	USPAT; US-PGPUB	2003/05/30 10:54
-	0	c23c016\$.ipc. and ((transfer\$4 with chamber with (inlet suppl\$3) with (vapor gas)) same align\$4)	EPO; JPO; DERWENT	2003/05/30 10:54
-	1	c23c016\$.ipc. and ((transfer\$4 with chamber with (inlet suppl\$3) with (vapor gas)) and align\$4)	EPO; JPO; DERWENT	2003/05/30 10:55
-	33	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ((transfer\$4 with chamber with (inlet suppl\$3) with (vapor gas)) and align\$4)	USPAT; US-PGPUB	2003/05/30 11:12
-	0	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer\$4 with chamber with (teflon ((silicon with carbide) "sic") polytetrafluoroethylene (resin\$3 with polymer\$3)))	USPAT; US-PGPUB	2003/05/30 11:20
-	0	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer\$4 with chamber with (teflon))	USPAT; US-PGPUB	2003/05/30 11:21

-	0	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer\$4 with chamber with ((silicon with carbide) "sic"))	USPAT; US-PGPUB	2003/05/30 11:22
-	0	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer\$4 with chamber with polytetrafluoroethylene)	USPAT; US-PGPUB	2003/05/30 11:21
-	0	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer\$4 with chamber with resin\$3 with polymer\$3)	USPAT; US-PGPUB	2003/05/30 11:22
-	48150	c23c016\$.ipc.	EPO; JPO; DERWENT	2003/05/30 16:32
-	0	c23c016\$.ipc. and (transfer\$4 with chamber with (teflon))	EPO; JPO; DERWENT	2003/05/30 11:22
-	0	c23c016\$.ipc. and (transfer\$4 with chamber with polytetrafluoroethylene)	EPO; JPO; DERWENT	2003/05/30 11:24
-	0	c23c016\$.ipc. and (transfer\$4 with chamber with ((silicon with carbide) "sic"))	EPO; JPO; DERWENT	2003/05/30 11:25
-	0	c23c016\$.ipc. and (transfer\$4 with chamber with resin\$3 with polymer\$3)	EPO; JPO; DERWENT	2003/05/30 11:24
-	10	c23c016\$.ipc. and (chamber with (teflon))	EPO; JPO; DERWENT	2003/05/30 11:22
-	0	c23c016\$.ipc. and (chamber with resin\$3 with polymer\$3)	EPO; JPO; DERWENT	2003/05/30 11:24
-	6	c23c016\$.ipc. and (chamber with polytetrafluoroethylene)	EPO; JPO; DERWENT	2003/05/30 11:24
-	116	c23c016\$.ipc. and (chamber with ((silicon with carbide) "sic"))	EPO; JPO; DERWENT	2003/05/30 11:25
-	4	c23c016\$.ipc. and (chamber with ((silicon with carbide) "sic") with corros\$3)	EPO; JPO; DERWENT	2003/05/30 11:25
-	0	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer\$4 with chamber with "hf")	USPAT; US-PGPUB	2003/05/30 16:30
-	1	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer\$4 with chamber with "acid")	USPAT; US-PGPUB	2003/05/30 16:14
-	0	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer\$4 with chamber with "hydroflouric")	USPAT; US-PGPUB	2003/05/30 16:15
-	1	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer\$4 with chamber with "hydrofluoric")	USPAT; US-PGPUB	2003/05/30 16:15
-	1715	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.	USPAT; US-PGPUB	2003/05/30 18:05
-	670	transfer\$4 with chamber with clean\$3 with (wafer substrate semiconductor)	USPAT; US-PGPUB	2003/05/30 16:36
-	48150	c23c016\$.ipc.	EPO; JPO; DERWENT	2003/05/30 16:32
-	158	transfer\$4 with chamber with clean\$3 with (wafer substrate semiconductor)	EPO; JPO; DERWENT	2003/05/30 16:32
-	0	c23c016\$.ipc. and (transfer\$4 with chamber with clean\$3 with (wafer substrate semiconductor))	USPAT; US-PGPUB	2003/05/30 16:36
-	12	c23c016\$.ipc. and (transfer\$4 with chamber with clean\$3 with (wafer substrate semiconductor))	EPO; JPO; DERWENT	2003/05/30 16:36
-	91	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer\$4 with chamber with clean\$3 with (wafer substrate semiconductor))	USPAT; US-PGPUB	2003/05/30 16:47
-	51	5259881.URPN.	USPAT	2003/05/30 17:00
-	6	("5228206" "5972161" "6143081" "6178660" "6204120" "6232248").PN.	USPAT	2003/05/30 17:52
-	3	5972161.URPN.	USPAT	2003/05/30 17:56
-	5	("5240556" "5344525" "5554563" "5670421" "5830279").PN.	USPAT	2003/05/30 17:58
-	37	transfer with chamber with ("HF" hydrofluoric)	USPAT; US-PGPUB	2003/05/30 18:12

-	5	transfer with chamber with ("HF" hydrofluoric)	EPO; JPO; DERWENT	2003/05/30 18:13
-	46	(US-5766360-\$ or US-4816098-\$ or US-6027960-\$ or US-5939333-\$ or US-5897710-\$ or US-5877086-\$ or US-5271732-\$ or US-5236868-\$ or US-5202275-\$ or US-6467491-\$ or US-5981399-\$ or US-5551984-\$ or US-4426439-\$ or US-6178660-\$ or US-5972161-\$ or US-5695564-\$ or US-4883020-\$ or US-5462397-\$ or US-5474410-\$ or US-5527390-\$ or US-5740034-\$ or US-5609689-\$ or US-5879461-\$ or US-5882165-\$ or US-6143081-\$ or US-6528431-\$).did. or (US-6140247-\$ or US-5043299-\$ or US-5259881-\$ or US-5294572-\$ or US-6007675-\$ or US-6323463-\$ or US-5770263-\$).did. or (US-20030053893-\$ or US-20010050146-\$ or US-20010031556-\$ or US-20010009813-\$ or US-20010001298-\$ or US-20020034595-\$).did. or (JP-2000323425-\$ or JP-2002270518-\$ or JP-09157073-\$ or JP-2002164408-\$).did. or (WO-200070666-\$ or EP-430303-\$ or US-6007675-\$).did.	USPAT; USPAT; US-PGPUB; JPO; DERWENT	2003/05/30 18:15
-	18	((US-5766360-\$ or US-4816098-\$ or US-6027960-\$ or US-5939333-\$ or US-5897710-\$ or US-5877086-\$ or US-5271732-\$ or US-5236868-\$ or US-5202275-\$ or US-6467491-\$ or US-5981399-\$ or US-5551984-\$ or US-4426439-\$ or US-6178660-\$ or US-5972161-\$ or US-5695564-\$ or US-4883020-\$ or US-5462397-\$ or US-5474410-\$ or US-5527390-\$ or US-5740034-\$ or US-5609689-\$ or US-5879461-\$ or US-5882165-\$ or US-6143081-\$ or US-6528431-\$).did. or (US-6140247-\$ or US-5043299-\$ or US-5259881-\$ or US-5294572-\$ or US-6007675-\$ or US-6323463-\$ or US-5770263-\$).did. or (US-20030053893-\$ or US-20010050146-\$ or US-20010031556-\$ or US-20010009813-\$ or US-20010001298-\$ or US-20020034595-\$).did. or (JP-2000323425-\$ or JP-2002270518-\$ or JP-09157073-\$ or JP-2002164408-\$).did. or (WO-200070666-\$ or EP-430303-\$ or US-6007675-\$).did.) and (oxide with (remov\$3 clean\$3) with chamber)	USPAT; US-PGPUB	2003/05/30 18:24

-	3	((US-5766360-\$ or US-4816098-\$ or US-6027960-\$ or US-5939333-\$ or US-5897710-\$ or US-5877086-\$ or US-5271732-\$ or US-5236868-\$ or US-5202275-\$ or US-6467491-\$ or US-5981399-\$ or US-5551984-\$ or US-4426439-\$ or US-6178660-\$ or US-5972161-\$ or US-5695564-\$ or US-4883020-\$ or US-5462397-\$ or US-5474410-\$ or US-5527390-\$ or US-5740034-\$ or US-5609689-\$ or US-5879461-\$ or US-5882165-\$ or US-6143081-\$ or US-6528431-\$).did. or (US-6140247-\$ or US-5043299-\$ or US-5259881-\$ or US-5294572-\$ or US-6007675-\$ or US-6323463-\$ or US-5770263-\$).did. or (US-20030053893-\$ or US-20010050146-\$ or US-20010031556-\$ or US-20010009813-\$ or US-20010001298-\$ or US-20020034595-\$).did. or (JP-2000323425-\$ or JP-2002270518-\$ or JP-09157073-\$ or JP-2002164408-\$).did. or (WO-200070666-\$ or EP-430303-\$ or US-6007675-\$).did.) and (transfer\$3 same rotat\$3 same align\$3)	USPAT; US-PGPUB	2003/05/30 18:24
-	0	(c23c016\$.ipc. h011021\$.ipc.) same (outlet with plural\$3 with (even\$3))	EPO; JPO; DERWENT	2003/06/02 08:30
-	2	(transfer with chamber) same (outlet with plural\$3 with (even\$3))	USPAT; US-PGPUB	2003/06/02 08:22
-	1715	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.	USPAT; US-PGPUB	2003/06/02 08:23
-	0	("5 and ((gas vapor) with (plural\$3 multipl\$3) with even\$3)").PN.	USPAT; US-PGPUB	2003/06/02 08:28
-	16	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ((gas vapor) with (plural\$3 multipl\$3) with even\$3)	USPAT; US-PGPUB	2003/06/02 08:27
-	145	(118/\$.ccls. 156/345\$.ccls.) and ((gas vapor) with (plural\$3 multipl\$3) with even\$3)	USPAT; US-PGPUB	2003/06/02 08:28
-	175	(c23c016\$.ipc. h011021\$.ipc.)and ((gas vapor) with (plural\$3 multipl\$3) with even\$3)	USPAT; US-PGPUB	2003/06/02 08:28
-	0	(c23c016\$.ipc. h011021\$.ipc.)and ((gas vapor) with (plural\$3 multipl\$3) with even\$3)	EPO; JPO; DERWENT	2003/06/02 08:30
-	0	(c23c016\$.ipc. h011021\$.ipc.)and ((gas vapor) with (plural\$3 multipl\$3) with (outlet inlet hole orifice))	EPO; JPO; DERWENT	2003/06/02 08:29
-	0	(c23c016\$.ipc. h011021\$.ipc.)and ((gas vapor) same (plural\$3 multipl\$3) same (outlet inlet hole orifice))	EPO; JPO; DERWENT	2003/06/02 08:29
-	0	(c23c016\$.ipc. h011021\$.ipc.) and ((gas vapor) same (plural\$3 multipl\$3) same (outlet inlet hole orifice))	EPO; JPO; DERWENT	2003/06/02 08:29
-	48150	c23c016\$.ipc.	EPO; JPO; DERWENT	2003/06/02 08:30
-	742155	h011021\$.ipc.	EPO; JPO; DERWENT	2003/06/02 08:30
-	0	(c23c016\$.ipc. h011021\$.ipc.) same (outlet with plural\$3 with (even\$3))	EPO; JPO; DERWENT	2003/06/02 09:10
-	5	(c23c016\$.ipc. h011021\$.ipc.) and (outlet with plural\$3 with (even\$3))	EPO; JPO; DERWENT	2003/06/02 08:31
-	82	(c23c016\$.ipc. h011021\$.ipc.)and ((gas vapor) with (plural\$3 multipl\$3) with even\$3)	EPO; JPO; DERWENT	2003/06/02 08:32
-	70	118/\$.ccls. and (oxide with remov\$3)	EPO; JPO; DERWENT	2003/06/02 09:11
-	667	118/\$.ccls. and (oxide with remov\$3)	USPAT; US-PGPUB	2003/06/02 09:11
-	159	118/\$.ccls. and (oxide with remov\$3 with chamber)	USPAT; US-PGPUB	2003/06/02 09:12
-	27	118/\$.ccls. and (oxide with remov\$3 with chamber with transfer\$4)	USPAT; US-PGPUB	2003/06/02 09:13

-	151	((transfer\$4 transport\$4) with chamber with (substrate wafer semiconductor) with (vapor\$4))	EPO; JPO; DERWENT	2003/11/20 13:49
-	624	((transfer\$4 transport\$4) with chamber with (substrate wafer semiconductor) with (vapor\$4))	USPAT; US-PGPUB	2003/11/20 13:38
-	68	("transfer chamber" with (substrate wafer semiconductor) with (vapor\$4))	USPAT; US-PGPUB	2003/11/20 13:38
-	17	((transfer\$4 adj chamber) with (substrate wafer semiconductor) with (vapor\$4))	EPO; JPO; DERWENT	2003/11/20 14:26
-	0	("transfer\$4 chamber" with (vapor\$4))	EPO; JPO; DERWENT	2003/11/20 14:01
-	161	("transfer chamber" with (vapor\$4))	USPAT; US-PGPUB	2003/11/20 14:21
-	37	("transfer chamber" with (vapor\$4) with (expos\$3 introduc\$3 inlet outlet supplied supply\$3))	USPAT; US-PGPUB	2003/11/20 14:04
-	124	((("transfer chamber" with (vapor\$4))) not (("transfer chamber" with (vapor\$4) with (expos\$3 introduc\$3 inlet outlet supplied supply\$3)))	USPAT; US-PGPUB	2003/11/20 14:21
-	1811	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.	USPAT; US-PGPUB	2003/11/20 15:04
-	8	(vapor with (supply\$3 suppli\$3) with transfer\$4 and ((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.)	USPAT; US-PGPUB	2003/11/20 14:25
-	0	"vapor inlet" with "transfer chamber"	EPO; JPO; DERWENT	2003/11/20 14:27
-	0	"vapor inlet" with "transfer chamber"	USPAT; US-PGPUB	2003/11/20 14:27
-	1	"vapor port" with "transfer chamber"	USPAT; US-PGPUB	2003/11/20 14:27
-	0	"vapor hole" with "transfer chamber"	USPAT; US-PGPUB	2003/11/20 14:27
-	2	"vapor outlet" with "transfer chamber"	USPAT; US-PGPUB	2003/11/20 14:28
-	5	(vapor\$4 adj (inlet hole port outlet conduit entrance introduc\$3 outlet aperture opening exit orifice vent\$3)) with "transfer chamber"	USPAT; US-PGPUB	2003/11/20 14:31
-	6	("4490209" "5007982" "5605603" "5854137" "5874362" "6242350").PN.	USPAT	2003/11/20 14:32
-	6	(vapor\$4 with (inlet hole port outlet conduit entrance introduc\$3 outlet aperture opening exit orifice vent\$3)) with "transfer chamber"	EPO; JPO; DERWENT	2003/11/20 14:34
-	25	(vapor\$4 with (inlet hole port outlet conduit entrance introduc\$3 outlet aperture opening exit orifice vent\$3) with transfer\$4) and c23c016\$.ipc.	EPO; JPO; DERWENT	2003/11/20 14:41
-	32	427/335.ccls.	EPO; JPO; DERWENT	2003/11/20 14:42
-	3	427/335.ccls. and (transfer\$3 with chamber)	USPAT; US-PGPUB	2003/11/20 14:42
-	208	427/335.ccls.	USPAT; US-PGPUB	2003/11/20 14:45
-	19	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ("hydrofluoric acid" "hf") with vapor\$4	USPAT; US-PGPUB	2003/11/20 15:55
-	2	118/719.ccls. and imahashi.in.	USPAT; US-PGPUB	2003/11/20 15:00
-	0	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ("transfer chamber" with (vaporiser vaporizer))	USPAT; US-PGPUB	2003/11/20 15:05
-	0	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer\$3 with chamber with (vaporiser vaporizer))	USPAT; US-PGPUB	2003/11/20 15:07
-	10	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer\$3 with chamber with remov\$4 with oxide)	USPAT; US-PGPUB	2003/11/20 15:09

-	39	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (transfer\$3 with chamber with oxide)	USPAT; US-PGPUB	2003/11/20 15:09
-	16	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ("transfer chamber" with oxide)	USPAT; US-PGPUB	2003/11/20 15:14
-	92	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ("transfer chamber" with gas)	USPAT; US-PGPUB	2003/11/20 15:18
-	9	c23c016\$.ipc. and ("transfer chamber" with (remov\$3 clean\$3))	EPO; JPO; DERWENT	2003/11/20 15:19
-	79	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ("transfer chamber" with (remov\$3 clean\$3))	USPAT; US-PGPUB	2003/11/20 15:49
-	6	("5228206" "5972161" "6143081" "6178660" "6204120" "6232248").PN.	USPAT	2003/11/20 15:38
-	3	5972161.URPN.	USPAT	2003/11/20 15:39
-	0	6467491.URPN.	USPAT	2003/11/20 15:39
-	13	("4795299" "4917556" "5228206" "5423971" "5529657" "5611861" "5755938" "5759334" "5855675" "5863170" "5880924" "5882165" "5886864").PN.	USPAT	2003/11/20 15:42
-	0	6467491.URPN.	USPAT	2003/11/20 15:43
-	6	("5228206" "5972161" "6143081" "6178660" "6204120" "6232248").PN.	USPAT	2003/11/20 15:43
-	11	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ("transfer chamber" with etch)	USPAT; US-PGPUB	2003/11/20 15:51
-	0	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ("transfer chamber" with "pre-process")	USPAT; US-PGPUB	2003/11/20 15:52
-	3	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ("transfer chamber" with "pre-processing")	USPAT; US-PGPUB	2003/11/20 15:52
-	0	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ("hydrofluoric acid" "hf") with "transfer chamber")	USPAT; US-PGPUB	2003/11/20 15:58
-	195	118/\$.ccls. and (transfer\$4 with chamber with expos\$4)	USPAT; US-PGPUB	2003/11/20 15:59
-	49	118/\$.ccls. and (transfer\$4 adj chamber with expos\$4)	USPAT; US-PGPUB	2003/11/20 15:59
-	49	118/\$.ccls. and ((transfer\$4 adj chamber) with expos\$4)	USPAT; US-PGPUB	2003/11/20 16:04
-	1	118/\$.ccls. and ((transfer\$4 adj chamber) with acid)	USPAT; US-PGPUB	2003/11/20 16:04
-	1	("5043299").PN.	USPAT; US-PGPUB	2003/11/21 10:55

-	64	(US-5766360-\$ or US-4816098-\$ or US-6528431-\$ or US-6140247-\$ or US-6027960-\$ or US-5939333-\$ or US-5897710-\$ or US-5877086-\$ or US-5271732-\$ or US-5236868-\$ or US-5202275-\$ or US-5043299-\$ or US-6467491-\$ or US-6083566-\$ or US-5981399-\$ or US-5551984-\$ or US-4883020-\$ or US-4426439-\$ or US-6178660-\$ or US-6143081-\$ or US-5972161-\$ or US-5882165-\$ or US-5695564-\$ or US-6183564-\$ or US-5879461-\$ or US-5740034-\$).did. or (US-5609689-\$ or US-5527390-\$ or US-5474410-\$ or US-5462397-\$ or US-6039811-\$ or US-6007675-\$ or US-5294572-\$ or US-5259881-\$ or US-6323463-\$ or US-5770263-\$ or US-4565157-\$ or US-4262631-\$ or US-5314574-\$ or US-6578589-\$ or US-6221742-\$ or US-6132564-\$ or US-6358859-\$ or US-4386119-\$ or US-4834020-\$).did. or (US-20030053893-\$ or US-20010031556-\$ or US-20010009813-\$ or US-20010001298-\$ or US-20010050146-\$ or US-20020034595-\$ or US-20020069899-\$ or US-20020020429-\$ or US-20010017103-\$ or US-20020184896-\$).did. or (JP-2000323425-\$ or JP-2002270518-\$ or JP-09157073-\$ or JP-2002164408-\$ or JP-61054628-\$).did. or (WO-200070666-\$ or US-6007675-\$ or EP-430303-\$ or US-20010031556-\$).did.	USPAT; US-PGPUB; JPO; DERWENT	2003/11/21 13:22
-	291	(427/\$.ccls. 438/\$.ccls.) and (transfer\$4 with chamber with vapor\$4)	USPAT; US-PGPUB; JPO; DERWENT	2003/11/21 11:03
-	38	(427/\$.ccls. 438/\$.ccls.) and ((transfer\$4 adj chamber) with vapor\$4)	USPAT; US-PGPUB; JPO; DERWENT	2003/11/21 11:03
-	40	(427/\$.ccls. 438/\$.ccls.) and ((transfer\$4 adj chamber) with (vapor\$4 "hf" "hydrofluoric" "hydrogen fluoride"))	USPAT; US-PGPUB; JPO; DERWENT	2003/11/21 11:19
-	6	("4490209" "5007982" "5605603" "5854137" "5874362" "6242350").PN.	USPAT	2003/11/21 11:11
-	1	(427/\$.ccls. 438/\$.ccls.) and ((transfer\$4 adj chamber) with ("etching gas"))	USPAT; US-PGPUB; JPO; DERWENT	2003/11/21 11:21
-	1	(427/\$.ccls. 438/\$.ccls.) and ((transfer\$4 adj chamber) with (etch\$3 with (while during)))	USPAT; US-PGPUB	2003/11/21 11:23
-	25	(427/\$.ccls. 438/\$.ccls.) and ((transfer\$4 adj chamber) with (remov\$3 with (layer film coating)))	USPAT; US-PGPUB	2003/11/21 11:24
-	8	(118/715-733.ccls. 156/345.\$.ccls.) and ((transfer\$4 adj chamber) with (remov\$3 with (layer film coating)))	USPAT; US-PGPUB	2003/11/21 11:29
-	44	5314574.URPN.	USPAT	2003/11/21 11:39
-	4	("4654106" "4857142" "5169408" "5248380").PN.	USPAT	2003/11/21 11:49
-	0	"09758610"	USPAT; US-PGPUB	2003/11/21 12:37
-	1	"09/758,610"	USPAT; US-PGPUB	2003/11/21 12:41
-	1	("6178660").PN.	USPAT; US-PGPUB	2003/11/21 12:41

-	2	((US-5766360-\$ or US-4816098-\$ or US-6528431-\$ or US-6140247-\$ or US-6027960-\$ or US-5939333-\$ or US-5897710-\$ or US-5877086-\$ or US-5271732-\$ or US-5236868-\$ or US-5202275-\$ or US-5043299-\$ or US-6467491-\$ or US-6083566-\$ or US-5981399-\$ or US-5551984-\$ or US-4883020-\$ or US-4426439-\$ or US-6178660-\$ or US-6143081-\$ or US-5972161-\$ or US-5882165-\$ or US-5695564-\$ or US-6183564-\$ or US-5879461-\$ or US-5740034-\$).did. or (US-5609689-\$ or US-5527390-\$ or US-5474410-\$ or US-5462397-\$ or US-6039811-\$ or US-6007675-\$ or US-5294572-\$ or US-5259881-\$ or US-6323463-\$ or US-5770263-\$ or US-4565157-\$ or US-4262631-\$ or US-5314574-\$ or US-6578589-\$ or US-6221742-\$ or US-6132564-\$ or US-6358859-\$ or US-4386119-\$ or US-4834020-\$).did. or (US-20030053893-\$ or US-20010031556-\$ or US-20010009813-\$ or US-20010001298-\$ or US-20010050146-\$ or US-20020034595-\$ or US-20020069899-\$ or US-20020020429-\$ or US-20010017103-\$ or US-20020184896-\$).did. or (JP-2000323425-\$ or JP-2002270518-\$ or JP-09157073-\$ or JP-2002164408-\$ or JP-61054628-\$).did. or (WO-200070666-\$ or US-6007675-\$ or EP-430303-\$ or US-20010031556-\$).did.) and (transfer with chamber with align)	USPAT; US-PGPUB; JPO; DERWENT	2003/11/21 14:02
-	0	pas-sylvia.in.	USPAT; US-PGPUB; JPO; DERWENT	2003/11/21 14:02
-	1	pas-sylvia-h.in.	USPAT; US-PGPUB	2003/11/21 14:03
-	3	pas-sylvia-\$.in.	USPAT; US-PGPUB	2003/11/21 14:03
-	1	("6391148").PN.	USPAT; US-PGPUB	2003/11/21 15:09
-	29	("transfer chamber" "transferring chamber") with vapor\$3	EPO; JPO; DERWENT	2004/05/04 11:23
-	174	("transfer chamber" "transferring chamber") with vapor\$3	USPAT; US-PGPUB	2004/05/04 12:00
-	116	((("transfer chamber" "transferring chamber") with vapor\$3) and (substrate wafer semiconductor)	USPAT; US-PGPUB	2004/05/04 12:02
-	117	((("transfer chamber" "transferring chamber") with vapor\$3) and (substrate wafer workpiece semiconductor)	USPAT; US-PGPUB	2004/05/04 12:03
-	0	((("vapor\$3 with solution) bubbler) with (transfer\$3 adj chamber)) and (414/\$.ccls. 118/\$.ccls. 216/\$.ccls. 427/\$.ccls.)	USPAT; US-PGPUB	2004/05/04 12:05
-	8	((("vapor\$3 with solution) bubbler) with (transfer\$3 adj chamber))	USPAT; US-PGPUB	2004/05/04 12:08
-	8	((("vapor\$3 with solution) bubbler) with (transfer\$4 adj chamber))	USPAT; US-PGPUB	2004/05/04 12:08
-	8	((("vapor\$3 with solution) bubbler) with (transfer\$4 adj chamber))	USPAT; US-PGPUB	2004/05/04 12:08
-	4	((("vapor\$3 with solution) bubbler) with (transfer\$4 adj chamber))	EPO; JPO; DERWENT	2004/05/04 12:10
-	180	(((" solution)) with (transfer\$4 adj chamber))	EPO; JPO; DERWENT	2004/05/04 12:10
-	116	(((" solution)) with (transfer\$4 adj chamber)) and (substrate workpiece wafer semiconductor)	EPO; JPO; DERWENT	2004/05/04 12:28
-	127	(gas\$4 with (transfer\$4 adj chamber)) and (substrate workpiece wafer semiconductor)	EPO; JPO; DERWENT	2004/05/04 12:11

-	14	(gas\$4 with solution with (transfer\$4 adj chamber)) and (substrate workpiece wafer semiconductor)	EPO; JPO; DERWENT	2004/05/04 12:27
-	0	(gas\$4 with solution with (transfer\$4 adj chamber)) and (substrate workpiece wafer semiconductor)	USPAT; US-PGPUB	2004/05/04 12:15
-	37	(solution with (transfer\$4 adj chamber)) and (substrate workpiece wafer semiconductor)	USPAT; US-PGPUB	2004/05/04 12:16
-	3	5983909.URPN.	USPAT	2004/05/04 12:19
-	3	5983909.URPN.	USPAT	2004/05/04 12:19
-	4	("5599438" "5616221" "5635053" "5676760").PN.	USPAT	2004/05/04 12:19
-	11	6039815.URPN.	USPAT	2004/05/04 12:20
-	6	("5190627" "5599438" "5616221" "5635053" "5676760" "5806126").PN.	USPAT	2004/05/04 12:21
-	0	"vaporous solution"	EPO; JPO; DERWENT	2004/05/04 12:27
-	0	(bubbler with (transfer\$4 adj chamber)) and (substrate workpiece wafer semiconductor)	EPO; JPO; DERWENT	2004/05/04 12:29
-	1	(bubbler with (transfer\$4 adj chamber)) and (substrate workpiece wafer semiconductor)	USPAT; US-PGPUB	2004/05/04 12:28
-	0	(vapor with (transfer\$4 adj chamber) with ("HF" "HBR" "HCL")) and (substrate workpiece wafer semiconductor)	EPO; JPO; DERWENT	2004/05/04 12:30
-	1	((transfer\$4 adj chamber) with ("HF" "HBR" "HCL")) and (substrate workpiece wafer semiconductor)	EPO; JPO; DERWENT	2004/05/04 12:31
-	5	(. (transfer\$4 adj chamber) with ("HF" "HBR" "HCL")) and (substrate workpiece wafer semiconductor)	USPAT; US-PGPUB	2004/05/04 12:32
-	0	((transfer\$4 adj chamber) with vapor with (liquid aqueous)) and (substrate workpiece wafer semiconductor)	EPO; JPO; DERWENT	2004/05/04 12:33
-	4	((transfer\$4 adj chamber) with vapor with (liquid aqueous)) and (substrate workpiece wafer semiconductor)	USPAT; US-PGPUB	2004/05/04 12:34
-	195	(((transfer\$4 transport\$3) with chamber) with vapor with (liquid aqueous)) and (substrate workpiece wafer semiconductor)	USPAT; US-PGPUB	2004/05/04 13:24
-	397	(((transfer\$4 transport\$3) adj chamber) with (clean\$3)) and (substrate workpiece wafer semiconductor)	USPAT; US-PGPUB	2004/05/04 13:25
-	8	(((transfer\$4 transport\$3) adj chamber) with (clean\$3) with vapor\$3) and (substrate workpiece wafer semiconductor)	USPAT; US-PGPUB	2004/05/04 13:28
-	397	(((transfer\$4 transport\$3) adj chamber) with (clean\$3)) and (substrate workpiece wafer semiconductor)	USPAT; US-PGPUB	2004/05/04 13:28
-	45	5314574.URPN.	USPAT	2004/05/04 13:31
-	116	(156/345.31.ccls. 156/345.32.ccls. 414/935-939.ccls. 118/719.ccls. 204/298.25.ccls. 204/298.26.ccls. 204/298.35.ccls.) and ((transfer\$4 transport\$3) adj chamber) same (solution aqueous liquid vapor\$3))	USPAT; US-PGPUB	2004/05/04 14:48
-	764	"hf vapor"	USPAT; US-PGPUB	2004/05/04 14:48
-	34	"hf vapor" and ((transfer\$4 transport\$3) adj chamber)	USPAT; US-PGPUB	2004/05/04 14:48
-	0	"hbr vapor" and ((transfer\$4 transport\$3) adj chamber)	USPAT; US-PGPUB	2004/05/04 14:48
-	0	("hbr vapor" "hbr vapor" "hcl vapor") with ((transfer\$4 transport\$3) adj chamber)	USPAT; US-PGPUB	2004/05/04 14:49
-	3	("hbr vapor" "hbr vapor" "hcl vapor") with (transfer\$4 transport\$3) with chamber	USPAT; US-PGPUB	2004/05/04 14:53
-	0	("hbr vapor" "hbr vapor" "hcl vapor") with (transfer\$4 transport\$3) with chamber	EPO; JPO; DERWENT	2004/05/04 14:52
-	5	("hbr" "hbr" "hcl") with vapor with (transfer\$4 transport\$3) with chamber	USPAT; US-PGPUB	2004/05/04 14:53

-	5	("hbr" "hbr" "hcl") with vapor\$5 with (transfer\$4 transport\$3) with chamber	USPAT;	2004/05/04 14:56
-	6	("4490209" "5007982" "5605603" "5854137" "5874362" "6242350").PN.	US-PGPUB	2004/05/04 14:55
-	1	("hbr" "hbr" "hcl") with vapor\$5 with (transfer\$4 transport\$3) with chamber	USPAT	2004/05/04 14:55
-	8	(acid\$2) with vapor\$5 with (transfer\$4 transport\$3) with chamber	EPO; JPO;	2004/05/04 14:57
-	28	(acid\$2) with vapor\$5 with (transfer\$4 transport\$3) with chamber	DERWENT	2004/05/04 14:57
-	404	kondo.in. and oxide and vapor	EPO; JPO;	2004/05/04 15:05
-	83	kondo.in. and oxide and vapor	DERWENT	2004/05/04 15:05
-	47	kondo.in. and oxide and vapor and (substrate wafer semiconductor workpiece)	USPAT;	2004/05/04 15:43
-	8	kondo.in. and oxide and vapor and (substrate wafer semiconductor workpiece) and acid\$3	US-PGPUB	2004/05/04 15:43
-	182	kondo.in. and oxide and vapor and (substrate wafer semiconductor workpiece) and acid\$3	US-PGPUB	2004/05/04 15:43
-	4	kondo.in. and (oxide same vapor same (substrate wafer semiconductor workpiece) same acid\$3)	EPO; JPO;	2004/05/04 15:43
-	43	5303671.URPN.	DERWENT	2004/05/04 15:44
-	1	"4592306".PN.	EPO; JPO;	2004/05/04 15:44
-	0	((("hbr vapor" "hbr vapor" "hcl vapor") with (transfer\$4 transport\$3) with chamber) and (vapor\$3 same acid\$3))	DERWENT	2004/05/04 15:49
-	0	((("hbr vapor" "hbr vapor" "hcl vapor") with (transfer\$4 transport\$3) with chamber) and (acid\$3))	EPO; JPO;	2004/05/04 15:49
-	0	((("hbr vapor" "hbr vapor" "hcl vapor") with (transfer\$4 transport\$3) with chamber) and (vapor\$3 same acid\$3)) and (vapor\$3 same acid\$3)	DERWENT	2004/05/04 15:49
-	2	5303671.URPN. and (vapor\$3 same acid\$3)	USPAT;	2004/05/04 15:49
-	7	5303671.URPN. and (acid\$3)	US-PGPUB	2004/05/04 15:52
-	18	5303671.URPN. and (vapor\$3)	USPAT;	2004/05/04 15:52
-	2	5303671.URPN. and (vapor\$3 with (transfer\$4 transport\$4))	US-PGPUB	2004/05/04 15:52
-	1	"4592306".PN.	USPAT;	2004/05/04 15:53
-	43	5303671.URPN.	USPAT	2004/05/04 15:51
-	1	10/265,899	USPAT	2004/05/04 15:51
-	1	10/265,699	USPAT;	2004/05/04 15:53
-	1	414/936.ccls. and (vapor\$3 with (acid "HF" "Hbr" "HCL"))	US-PGPUB	2004/05/04 15:52
-	11	5474641.URPN.	USPAT;	2004/05/04 15:52
-	173	(oxide with remov\$3) with transfer\$4 with chamber	US-PGPUB	2004/05/04 15:52